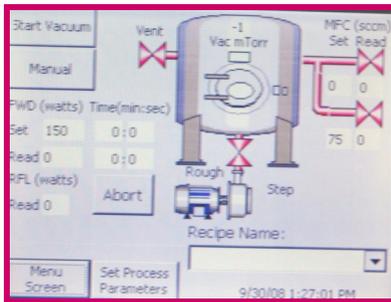
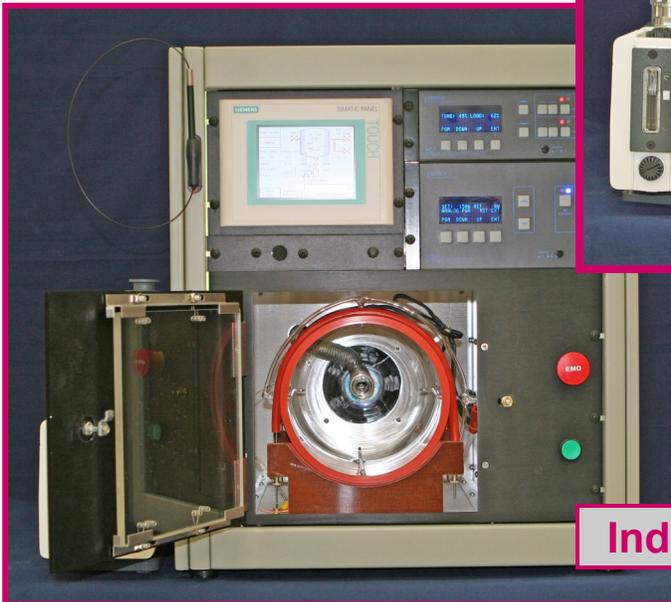
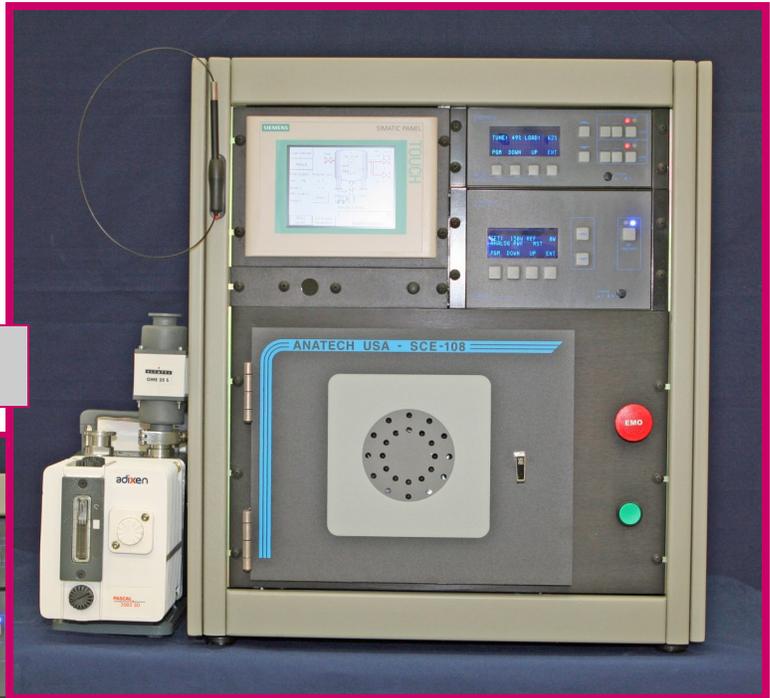




SCE-108 ICP Plasma System



**Optional: Siemens Multi-Process
"Touch Panel" Control, Password Protected**



**SCE-108 Shown with
RF Matching Network
Multi-Process PLC
Mass Flow Controls**

Inductively Coupled Plasma — ICP

"Ultra Clean" Quartz Chamber

There are no metal parts inside this chamber, your parts aren't exposed to the particulates associated with metal chambers.

**Immersing parts in low temperature plasma may be your final
Cleaning, Ashing, Etching solution !!**

Anatech's plasma systems are CFC and effluent free, operator and environmentally safe, easily operated.

SCE 108 ICP Plasma System Specifications

Control System : Standard System

Siemens S7-200 series PLC controlled
auto sequencing
Touch-Panel interface
On screen vacuum display –Pirani gauge
Gas flow control needle valve

Options:

Mass flow controller—up to 3-gasses
Multi-color touch screen
Multiple Process PLC with recipe
and & process memory

Facility Requirements:

115-VAC 20A 50/60-HZ Cabinet
115-VAC 20A 50/60-HZ Vacuum
60-PSI air
Process gas 5-8-PSI

Options:

220-VAC option available

Quartz Reactor Chamber:

8” diameter x 8” long quartz chamber
RF shielded
Front load
View port in door

Dimensions:

23” W x 26” H x 30” D
150 Lbs. Crated weight (estimated)

RF Power Source: Standard System

0-150 Watt RF 13.56 MHz supply
Manual RF Tuning
Forward and reflected power readings

Options:

Low frequency
Automatic RF Tuning, matching network
0-300 Watt RF with Auto Tuner for faster
processing time

Vacuum System:

3.8 CFM Standard service pumping
KF-16 Pneumatic valve for pump
isolation

Options:

Slow Pump Turbulence Reduction
Oxygen Service Class “B” Preparation

CALL ANATECH USA TODAY TO DISCUSS YOUR APPLICATION

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